

Title (en)  
Electrolyte for the deposition of an alloy and electrodeposition process

Title (de)  
Elektrolyt für die Abscheidung einer Legierung und Verfahren zur elektrolytischen Abscheidung

Title (fr)  
Electrolyte pour le dépôt d'un alliage et procédé de dépôt électrolytique

Publication  
**EP 1674662 A1 20060628 (DE)**

Application  
**EP 04030732 A 20041223**

Priority  
EP 04030732 A 20041223

Abstract (en)  
Electrolyte for electrodeposition of alloys in which the matrix material of the alloy is dissolved and containing another component in powder form. An independent claim is included for deposition of a layer from the electrolyte.

IPC 8 full level  
**F01D 5/28** (2006.01); **C25D 3/56** (2006.01); **C25D 15/02** (2006.01)

CPC (source: EP)  
**C22C 1/045** (2013.01); **C22C 19/05** (2013.01); **C22C 19/056** (2013.01); **C22C 19/058** (2013.01); **C22C 19/07** (2013.01); **C22C 27/06** (2013.01)

Citation (search report)  
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• [X] FR 2367833 A1 19780512 - BBC BROWN BOVERI & CIE [CH]  
• [X] WO 0036180 A1 20000622 - ONERA (OFF NAT AEROSPATIALE) [FR], et al  
• [XAY] EP 0484115 A1 19920506 - GEN ELECTRIC [US]  
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• [Y] JUN L ET AL: "MICROSTRUCTURE CHARACTERISTICS OF THE NICKEL MATRIX IN ELECTRODEPOSITED NI-PSZ GRADIENT COATING", TRANSACTIONS OF THE INSTITUTE OF METAL FINISHING, INSTITUTE OF METAL FINISHING, LONDON, GB, vol. 76, no. PART 4, July 1998 (1998-07-01), pages 131 - 134, XP000765554, ISSN: 0020-2967

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DOCDB simple family (publication)  
**EP 1674662 A1 20060628**; AT E426733 T1 20090415; DE 502005006969 D1 20090507; EP 1807554 A2 20070718; EP 1840334 A2 20071003; EP 1840334 A3 20071114; EP 1840335 A2 20071003; EP 1840335 A3 20071114; EP 1840335 B1 20090325; ES 2321236 T3 20090603; WO 2006069816 A2 20060706; WO 2006069816 A3 20070823

DOCDB simple family (application)  
**EP 04030732 A 20041223**; AT 07008970 T 20050929; DE 502005006969 T 20050929; EP 05801373 A 20050929; EP 07008969 A 20050929; EP 07008970 A 20050929; EP 2005054917 W 20050929; ES 07008970 T 20050929